Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

PART OBSOLETE – USE DMMT5401

IMT4

DUAL PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

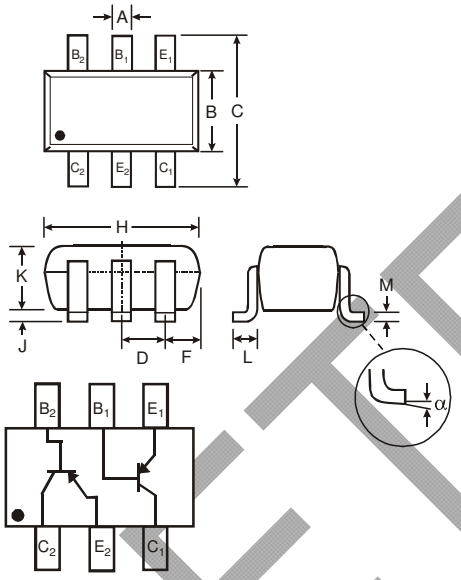
Lead-free Green

Features

- Epitaxial Planar Die Construction
- Complementary NPN Type Available (IMX8)
- Small Surface Mount Package
- **Lead Free/RoHS Compliant (Note 3)**
- **"Green" Device, Note 4 and 5**

Mechanical Data

- Case: SOT-26
- Case Material: Molded Plastic, "Green" Molding Compound, Note 5. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: See Diagram
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Copper leadframe).
- Marking Information: KX7 - See Page 3
- Ordering & Date Code Information: See Page 3
- Weight: 0.016 grams (approximate)



SOT-26			
Dim	**Min**	**Max**	**Typ**
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
F	—	—	0.55
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-120	V
Collector-Emitter Voltage	V_{CEO}	-120	V
Emitter-Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-50	mA
Power Dissipation (Note 1)	P_d	225	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	555	°C/W
Operating and Storage Temperature Range	T_j, T_{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 2)						
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	-120	—	—	V	I_C = -50μA
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	-120	—	—	V	I_C = -1.0mA
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	-5.0	—	—	V	I_E = -50μA
Collector Cutoff Current	I_{CBO}	—	—	-0.5	μA	V_{CB} = -100V
Emitter Cutoff Current	I_{EBO}	—	—	-0.5	μA	V_{EB} = -4.0V
ON CHARACTERISTICS (Note 2)						
DC Current Gain	h_{FE}	180	—	820	—	I_C = -2.0mA, V_{CE} = -6.0V
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	—	-0.5	V	I_C = -10mA, I_B = -1.0mA
SMALL SIGNAL CHARACTERISTICS						
Current Gain-Bandwidth Product	f_T	—	140	—	MHz	V_{CE} = -12V, I_C = -2.0mA, f = 100MHz

Notes:
1. Device mounted on FR-5 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf. 200mW per element must not be exceeded.
2. Short duration pulse test used to minimize self-heating effect.
3. No purposefully added lead.
4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
5. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

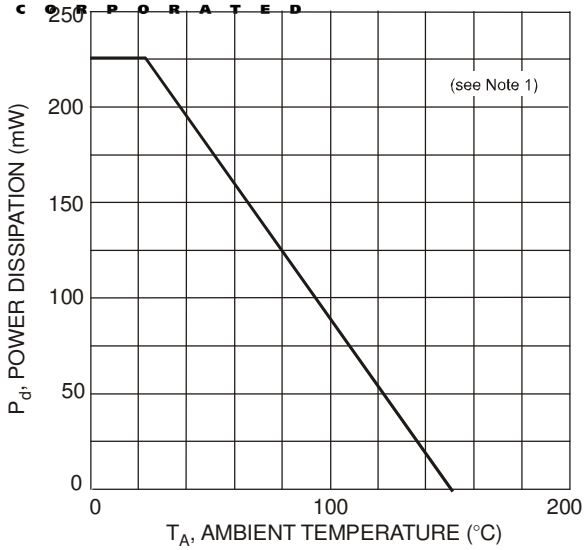


Fig. 1, Power Derating Curve

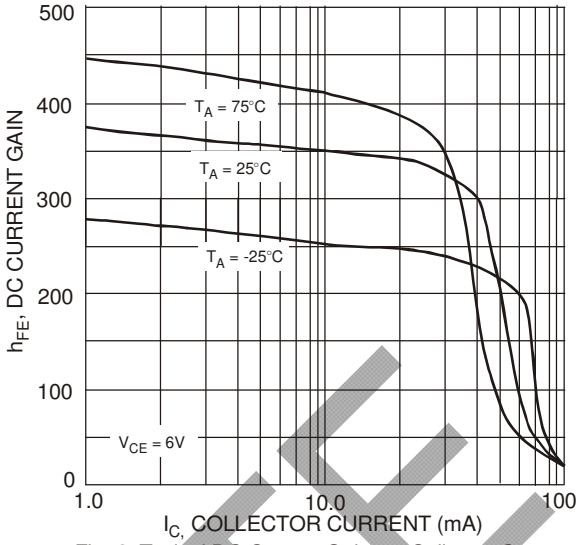


Fig. 2 Typical DC Current Gain vs. Collector Current

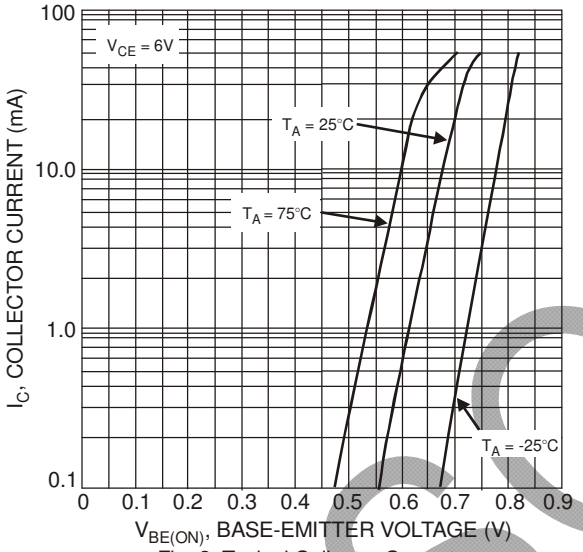


Fig. 3 Typical Collector Current vs. Base-Emitter Voltage

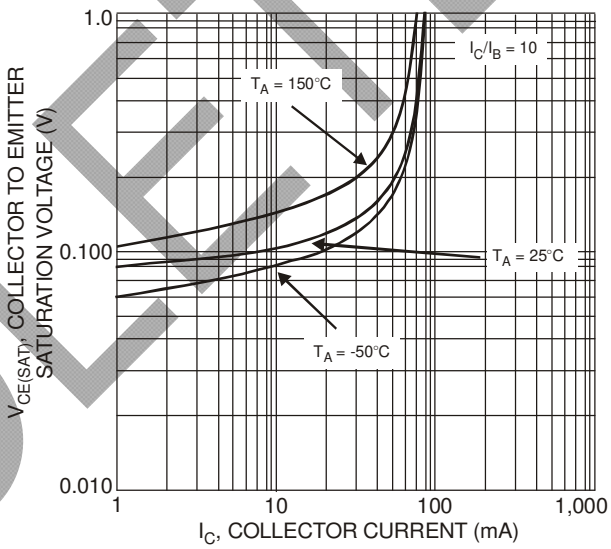


Fig. 4 Typical Collector-Emitter Voltage vs. Collector Current

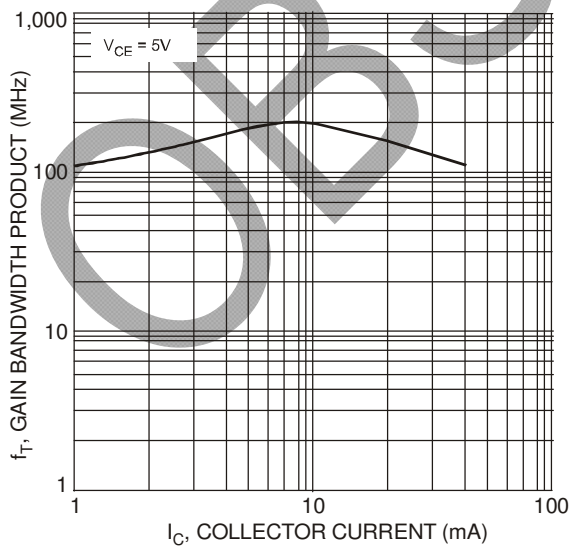


Fig. 5 Typical Gain Bandwidth Product vs. Collector Current

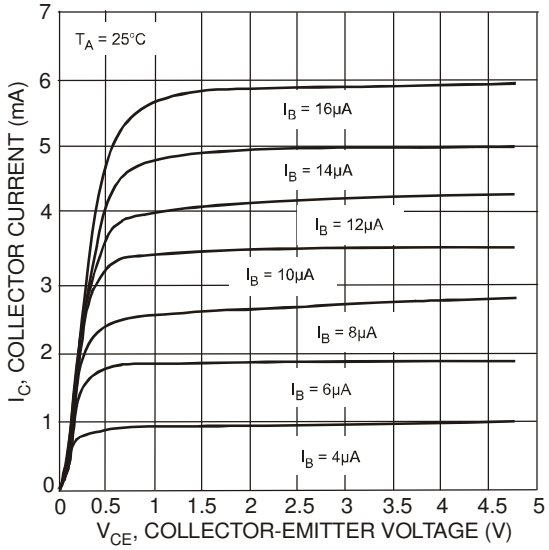


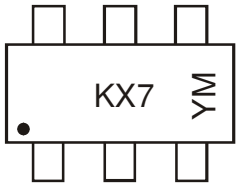
Fig. 6 Typical Collector Current vs. Collector-Emitter Voltage

Ordering Information (Note 5 & 6)

Device	Packaging	Shipping
IMT4-7-F	SOT-26	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



KX7 = Product Type Marking Code
YM = Date Code Marking
Y =Year ex: T = 2006
M = Month ex: 9 = September
YM = Date Code Marking

Date Code Key

Year	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	N	P	R	S	T	U	V	W	X	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D